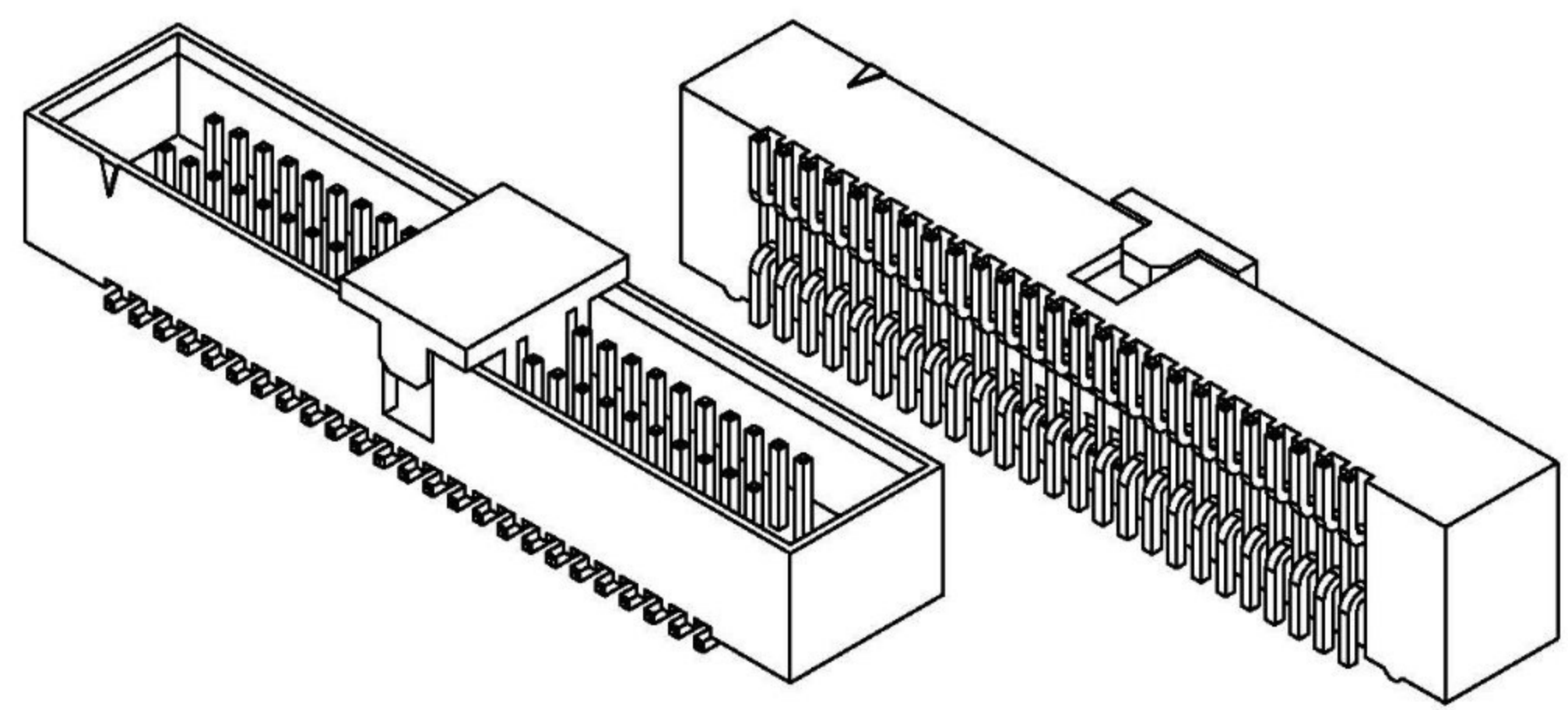


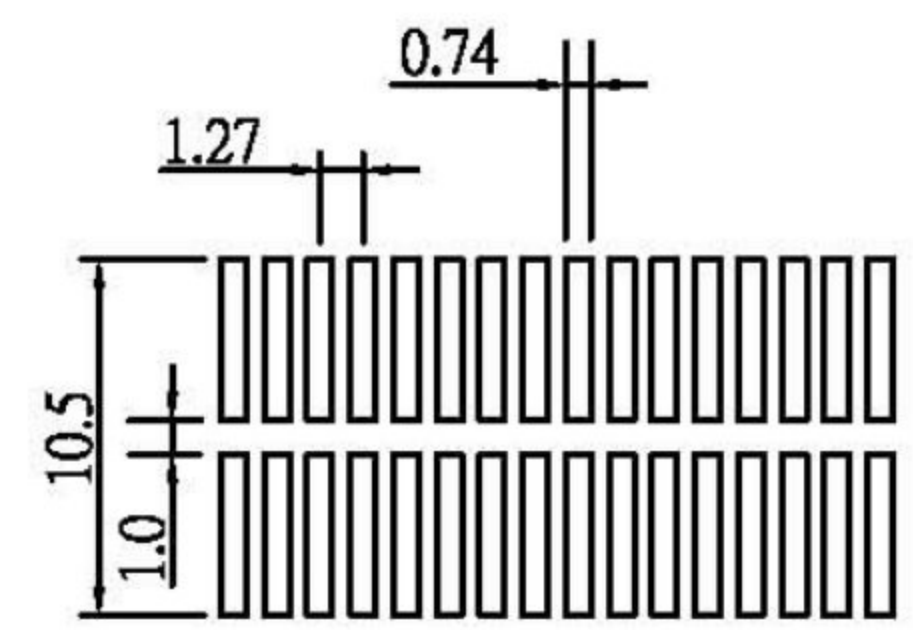
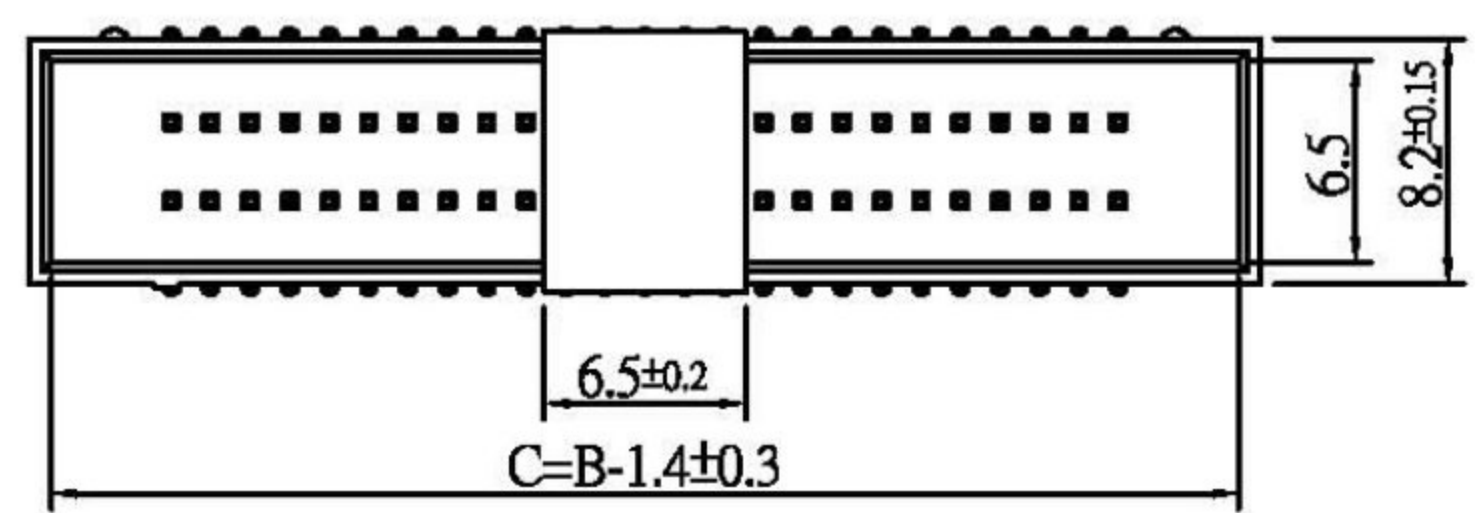
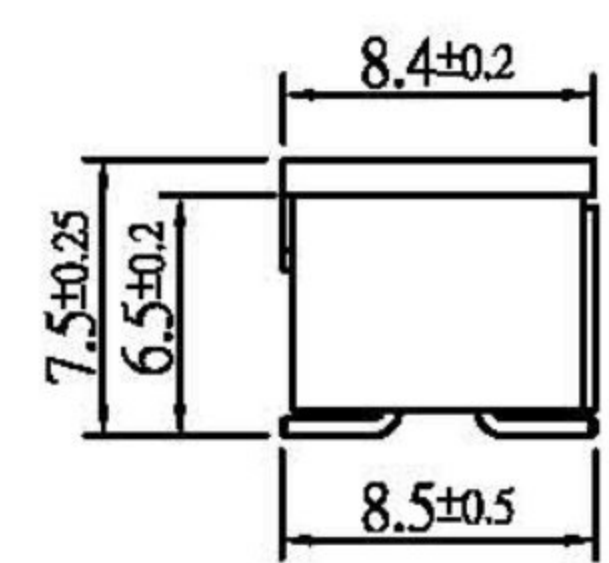
1 2 3 4 5 6 7 8

A  
B  
C  
D  
E  
F  
G  
H

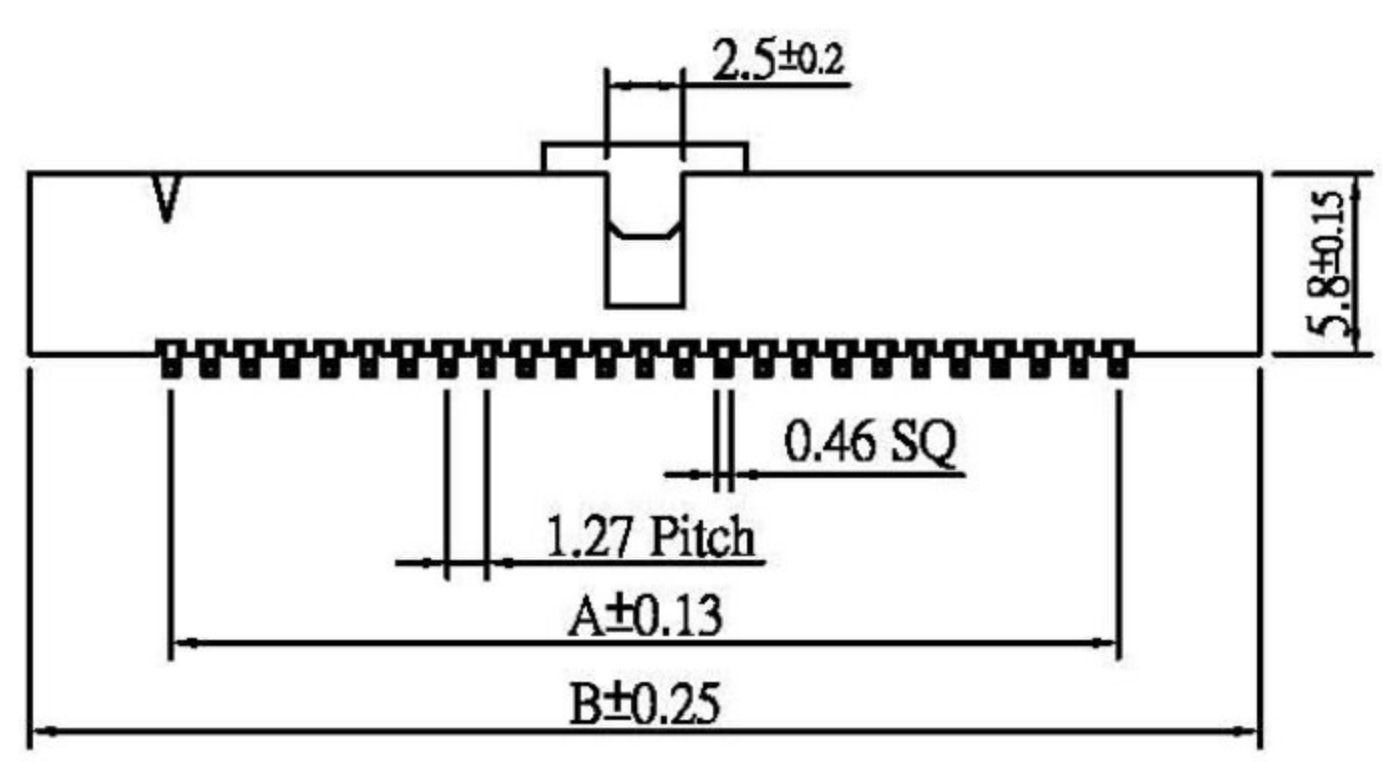
A  
B  
C  
D  
E  
F  
G  
H



Contact:  
Contact: Brass.  
Insulator: Nylon 6T.  
Finish: Gold flash plated over nickel.



P.C. Board Layout



Circuits	Dimension	
	A	B
08	3.81	13.10
10	5.08	14.37
16	8.89	18.18
20	11.43	20.72
26	15.24	24.53
30	17.78	27.07
34	20.32	29.61
40	24.13	33.42
44	26.67	35.96
50	30.48	39.77
60	36.83	46.12
68	41.91	51.20
80	49.53	58.82
100	62.23	71.52

<b>RoHS Compliant</b>		<b>HSM 玄茂科技股份有限公司</b> <b>HSUAN MAO TECHNOLOGY CO., LTD.</b>	
APPD. 核准 DWG. 製圖 HELEN DATE 創表日 2017/10/23	SCALE 比例 參考 UNIT 單位 MM PAGE 張數 1 OF 1	TOLERANCE 容許公差 .0 ± .00 ± ANG. ± SIZE 紙張尺寸 A4 REV. 版本 B	PART NAME 品名 BOX HEADER 1.27mm X 2.54mm XXP SMT TYPE GOLD PLATING BLACK COLOR (PAD+TUBE or PAD+REEL PACKING) ROHS LOW-LEAD PART NO. 料號 C3503-XXDGB00(P,Q)R

1 2 3 4 5 6 7 8